



S/N 10/775,890

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants:	Biswajit Sur et al.	Examiner:	Andy Huynh
Serial No.:	10/775,890	Group Art Unit:	2818
Filed:	February 9, 2004	Docket No.:	884.319US2
Title:	ELECTRONIC ASSEMBLY COMPRISING SOLDERABLE THERMAL INTERFACE AND METHODS OF MANUFACTURE		
Assignee:	Intel Corporation	Customer No:	21186

AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

MS Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

This responds to the Office Action mailed on July 26, 2005. Please amend the above-identified patent application as follows.

This response is accompanied by a Petition, as well as the appropriate fee, to obtain a two-month extension of the period for responding to the Office action, thereby moving the deadline for response from October 26, 2005 to December 26, 2005.